



NX7002BKM

60 V, N-channel Trench MOSFET

3 December 2014

Product data sheet

1. General description

N-channel enhancement mode Field-Effect Transistor (FET) in a leadless ultra small DFN1006-3 (SOT883) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Logic-level compatible
- Very fast switching
- Trench MOSFET technology
- ElectroStatic Discharge (ESD) protection > 2kV HBM

3. Applications

- Relay driver
- High-speed line driver
- Low-side loadswitch
- Switching circuits

4. Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|----------------------------------|---|-----|-----|-----|----------|
| V_{DS} | drain-source voltage | $T_j = 25\text{ }^\circ\text{C}$ | - | - | 60 | V |
| V_{GS} | gate-source voltage | | -20 | - | 20 | V |
| I_D | drain current | $V_{GS} = 10\text{ V}; T_{amb} = 25\text{ }^\circ\text{C}$ | [1] | - | 350 | mA |
| Static characteristics | | | | | | |
| $R_{DS(on)}$ | drain-source on-state resistance | $V_{GS} = 10\text{ V}; I_D = 200\text{ mA}; T_j = 25\text{ }^\circ\text{C}$ | - | 2.2 | 2.8 | Ω |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm^2 .

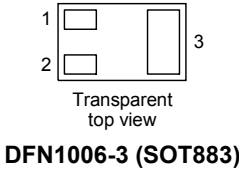
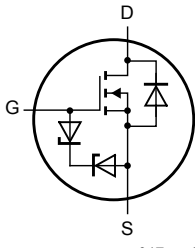


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5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|---|--|
| 1 | G | gate |  <p>Transparent top view DFN1006-3 (SOT883)</p> |  <p>017aaa255</p> |
| 2 | S | source | | |
| 3 | D | drain | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|-----------|---|---------|
| | Name | Description | Version |
| NX7002BKM | DFN1006-3 | DFN1006-3: leadless ultra small plastic package; 3 solder lands | SOT883 |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| NX7002BKM | WZ |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|---------------------------|-------------------------|--|-----|-----|------|------|
| V _{DS} | drain-source voltage | T _j = 25 °C | | - | 60 | V |
| V _{GS} | gate-source voltage | | | -20 | 20 | V |
| I _D | drain current | V _{GS} = 10 V; T _{amb} = 25 °C | [1] | - | 350 | mA |
| | | V _{GS} = 10 V; T _{amb} = 100 °C | [1] | - | 200 | mA |
| I _{DM} | peak drain current | T _{amb} = 25 °C; single pulse; t _p ≤ 10 μs | | - | 0.9 | A |
| P _{tot} | total power dissipation | T _{amb} = 25 °C | [2] | - | 350 | mW |
| | | | [1] | - | 680 | mW |
| | | T _{sp} = 25 °C | | - | 3100 | mW |
| T _j | junction temperature | | | -55 | 150 | °C |
| T _{amb} | ambient temperature | | | -55 | 150 | °C |
| T _{stg} | storage temperature | | | -65 | 150 | °C |
| Source-drain diode | | | | | | |
| I _S | source current | T _{amb} = 25 °C | [1] | - | 200 | mA |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm².

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

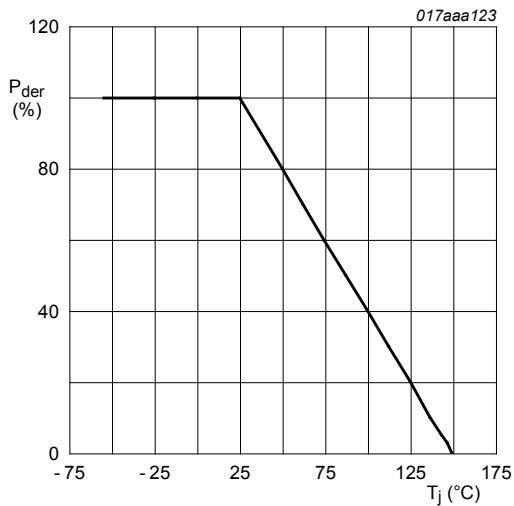


Fig. 1. Normalized total power dissipation as a function of junction temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100 \%$$

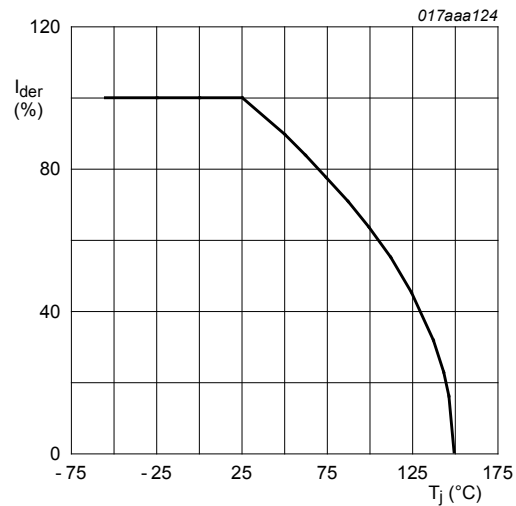
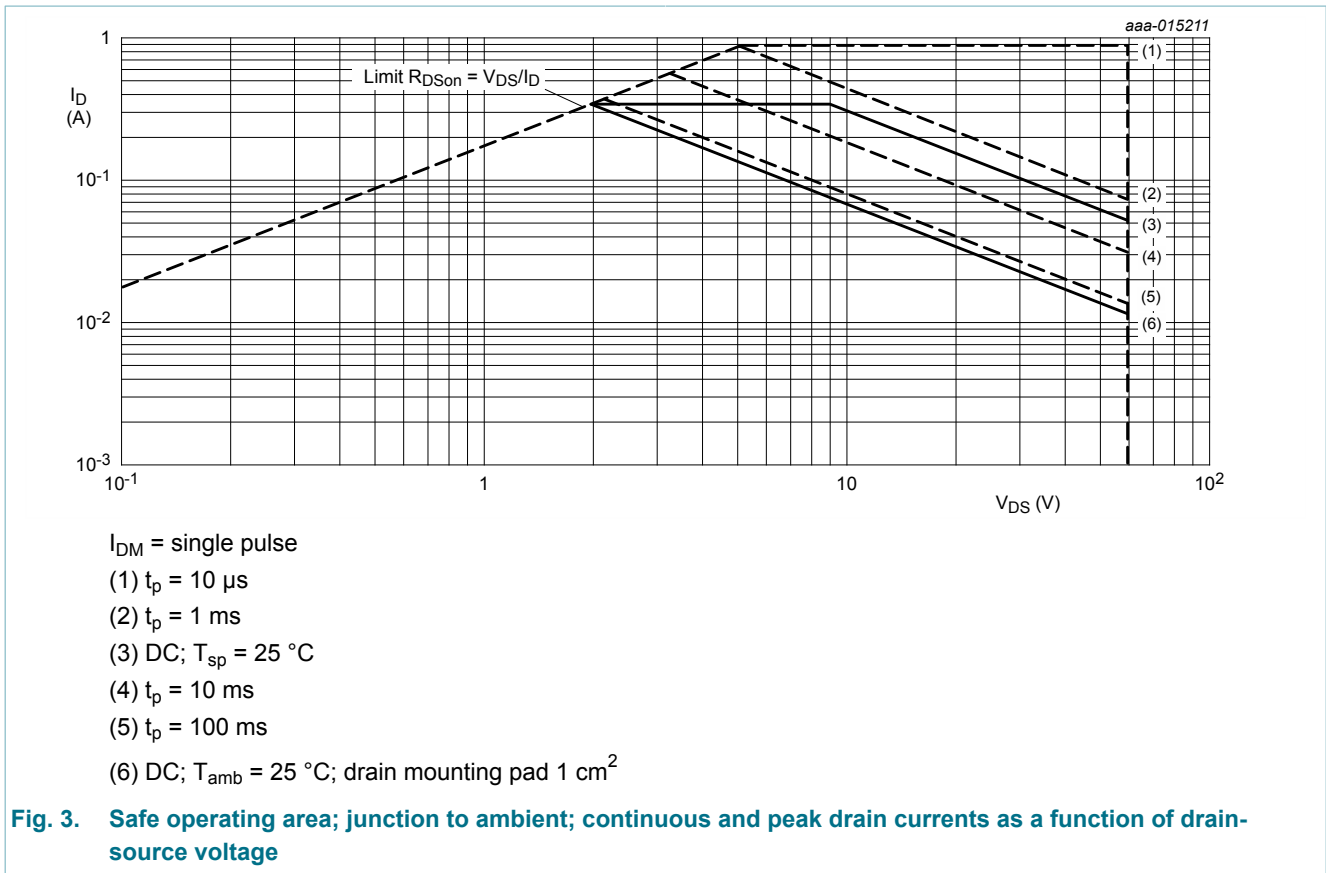


Fig. 2. Normalized continuous drain current as a function of junction temperature

$$I_{der} = \frac{I_D}{I_{D(25^{\circ}\text{C})}} \times 100 \%$$



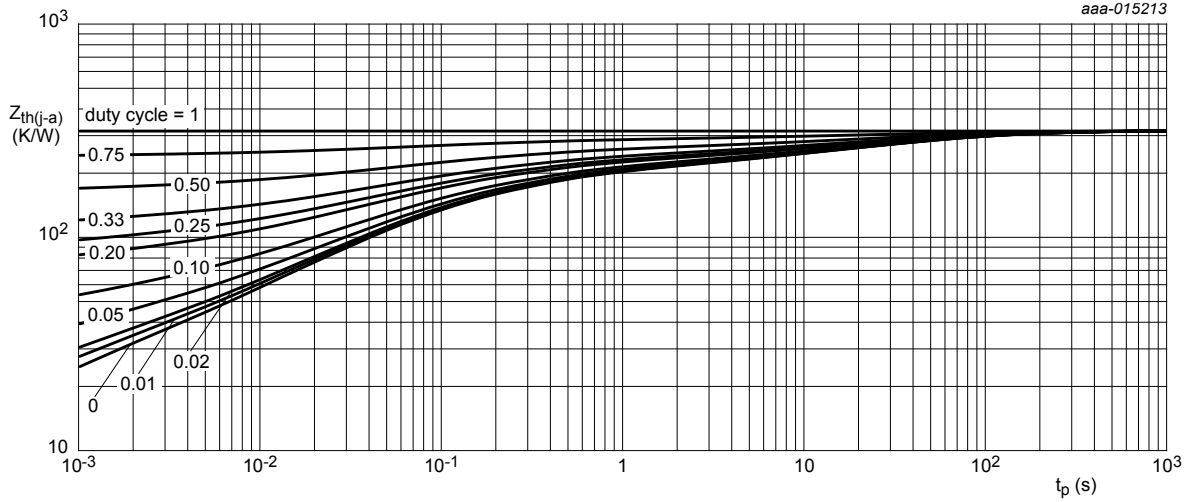
9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|----------------|--|-------------|-----|-----|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] | - | 314 | 360 | K/W |
| | | | [2] | - | 159 | 180 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | | - | 35 | 40 | K/W |

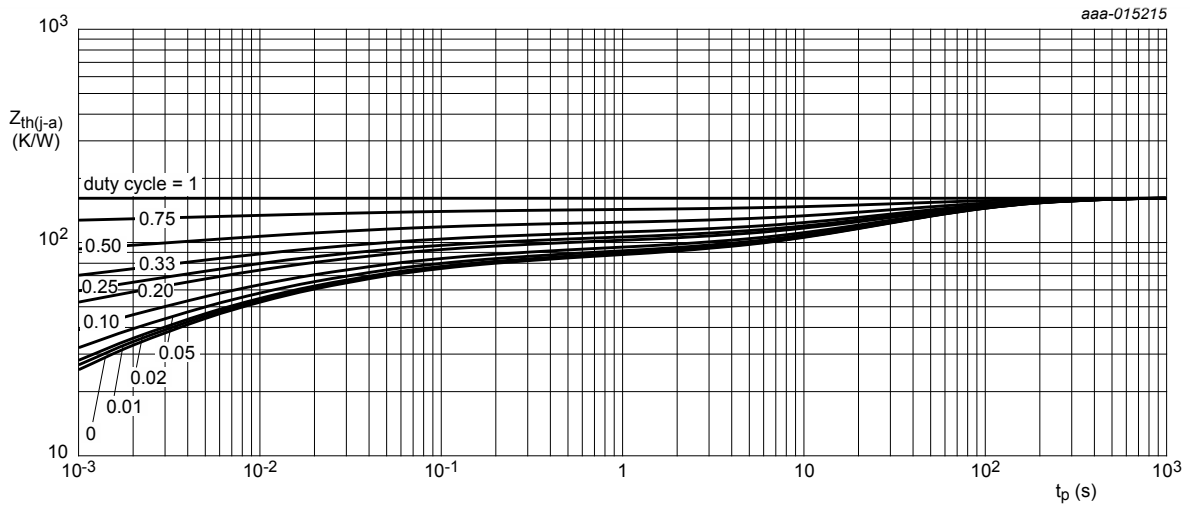
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 1 cm^2 .



FR4 PCB, standard footprint

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for drain 1 cm²

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|----------------------------------|---|---|------|-----|----------|
| Static characteristics | | | | | | |
| $V_{(BR)DSS}$ | drain-source breakdown voltage | $I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$ | 60 | - | - | V |
| V_{GSth} | gate-source threshold voltage | $I_D = 250 \mu A; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ C$ | 1.1 | 1.6 | 2.1 | V |
| I_{DSS} | drain leakage current | $V_{DS} = 60 V; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | - | 1 | μA |
| I_{GSS} | gate leakage current | $V_{GS} = 20 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | - | 10 | μA |
| | | $V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | - | -10 | μA |
| | | $V_{GS} = 10 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | - | 1 | μA |
| | | $V_{GS} = -10 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | - | -1 | μA |
| | | $V_{GS} = 5 V; V_{DS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | - | 0.3 | μA |
| R_{DSon} | drain-source on-state resistance | $V_{GS} = 10 V; I_D = 200 \text{ mA}; T_j = 25 \text{ }^\circ C$ | - | 2.2 | 2.8 | Ω |
| | | $V_{GS} = 10 V; I_D = 100 \text{ mA}; T_j = 150 \text{ }^\circ C$ | - | 4.5 | 5.7 | Ω |
| | | $V_{GS} = 5 V; I_D = 200 \text{ mA}; T_j = 25 \text{ }^\circ C$ | - | 2.5 | 3.2 | Ω |
| g_{fs} | forward transconductance | $V_{DS} = 10 V; I_D = 200 \text{ mA}; T_j = 25 \text{ }^\circ C$ | - | 600 | - | mS |
| R_G | internal gate resistance (AC) | $f = 2.5 \text{ MHz}$ | - | 2.5 | - | Ω |
| Dynamic characteristics | | | | | | |
| $Q_{G(tot)}$ | total gate charge | $V_{DS} = 30 V; I_D = 200 \text{ mA}; V_{GS} = 10 V; T_j = 25 \text{ }^\circ C$ | - | 1 | - | nC |
| Q_{GS} | gate-source charge | | - | 0.12 | - | nC |
| Q_{GD} | gate-drain charge | | - | 0.18 | - | nC |
| C_{iss} | input capacitance | $V_{DS} = 10 V; f = 1 \text{ MHz}; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | 23.6 | - | pF |
| C_{oss} | output capacitance | | - | 4.6 | - | pF |
| C_{rss} | reverse transfer capacitance | | - | 3 | - | pF |
| $t_{d(on)}$ | turn-on delay time | | $V_{DS} = 50 V; I_D = 200 \text{ mA}; V_{GS} = 10 V; R_{G(ext)} = 6 \text{ } \Omega; T_j = 25 \text{ }^\circ C$ | - | 4.7 | - |
| t_r | rise time | - | | 4.3 | - | ns |
| $t_{d(off)}$ | turn-off delay time | - | | 6.9 | - | ns |
| t_f | fall time | - | | 2.9 | - | ns |
| Source-drain diode | | | | | | |
| V_{SD} | source-drain voltage | $I_S = 200 \text{ mA}; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$ | - | 0.87 | 1.2 | V |

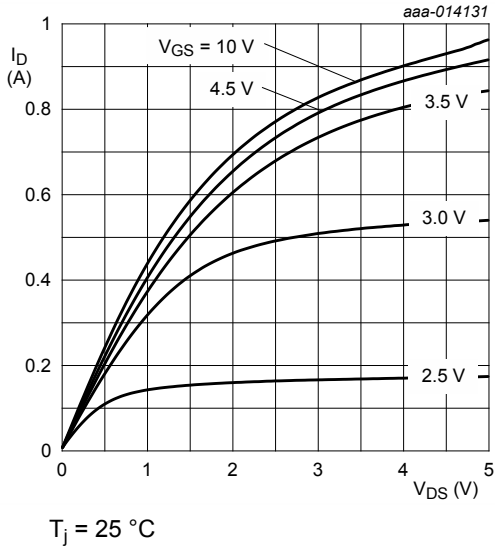


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

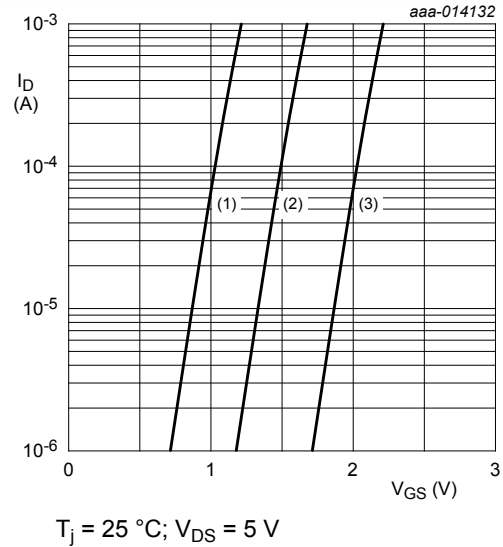


Fig. 7. Sub-threshold drain current as a function of gate-source voltage
 (1) minimum values
 (2) typical values
 (3) maximum values

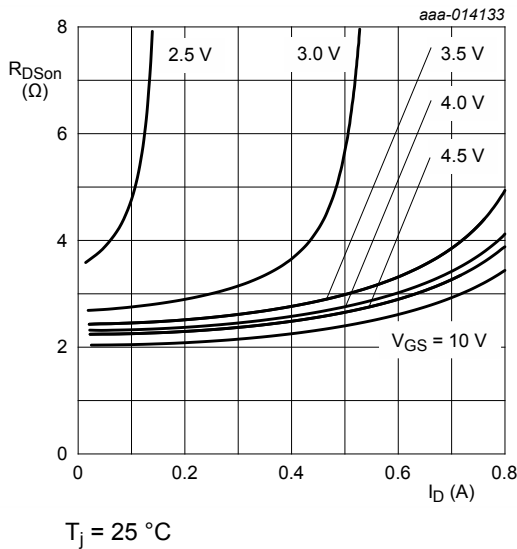


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

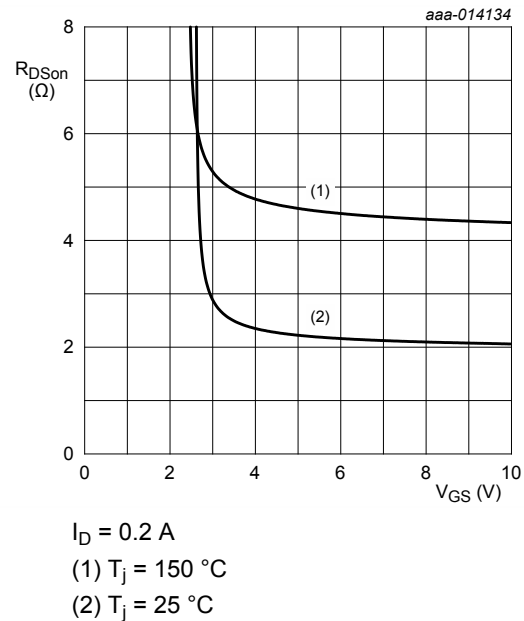
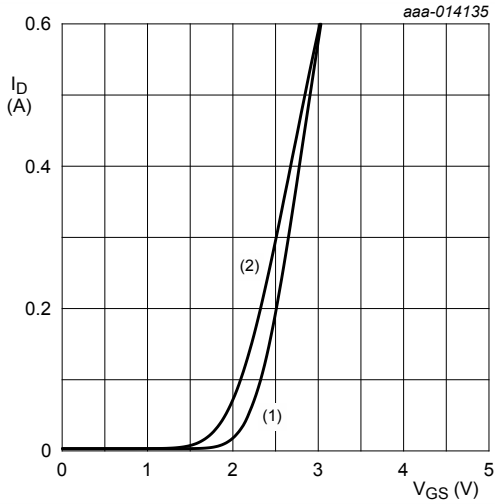


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values



$V_{DS} > I_D \times R_{DS(on)}$
 (1) $T_j = 25\text{ }^\circ\text{C}$
 (2) $T_j = 150\text{ }^\circ\text{C}$

Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

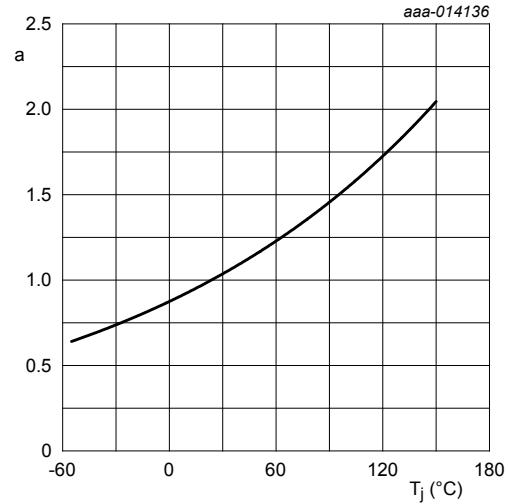
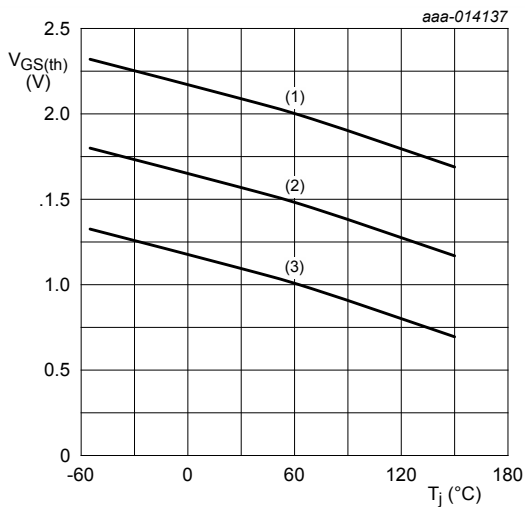


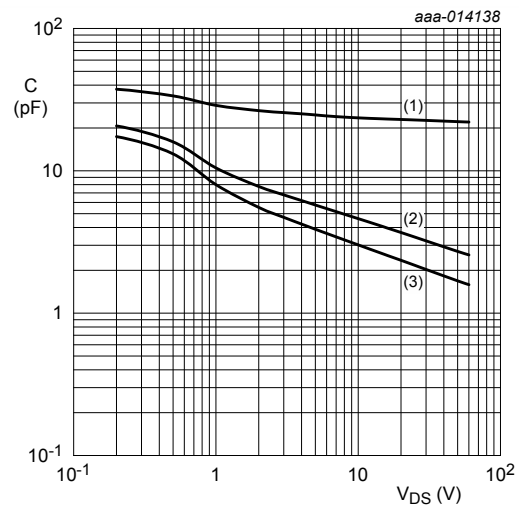
Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

$$a = \frac{R_{DS(on)}}{R_{DS(on)@25^\circ\text{C}}}$$



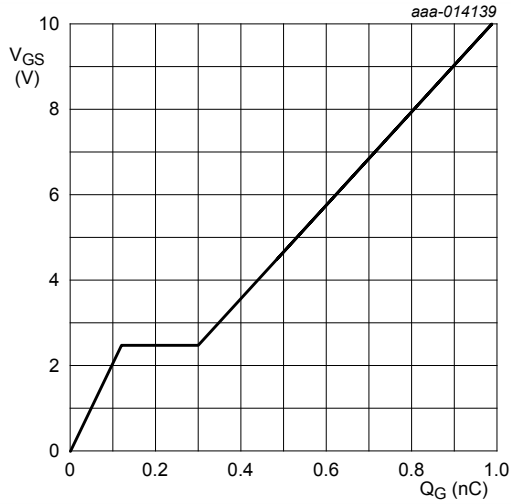
$I_D = 0.25\text{ mA}; V_{DS} = V_{GS}$
 (1) maximum values
 (2) typical values
 (3) minimum values

Fig. 12. Gate-source threshold voltage as a function of junction temperature



$f = 1\text{ MHz}; V_{GS} = 0\text{ V}$
 (1) C_{iss}
 (2) C_{oss}
 (3) C_{rss}

Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$I_D = 0.2 \text{ A}; V_{DS} = 30 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}$

Fig. 14. Gate-source voltage as a function of gate charge; typical values

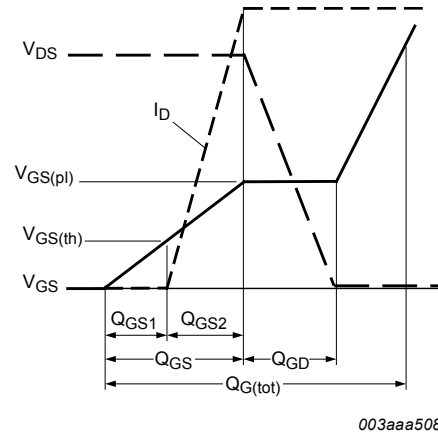
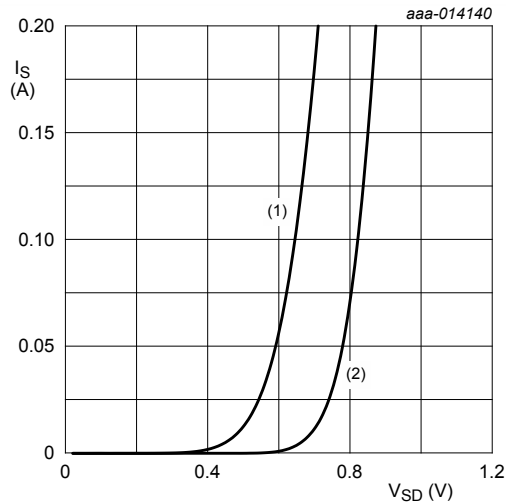


Fig. 15. MOSFET transistor: Gate charge waveform definitions



$V_{GS} = 0 \text{ V}$
 (1) $T_j = 150 \text{ }^\circ\text{C}$
 (2) $T_j = 25 \text{ }^\circ\text{C}$

Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information

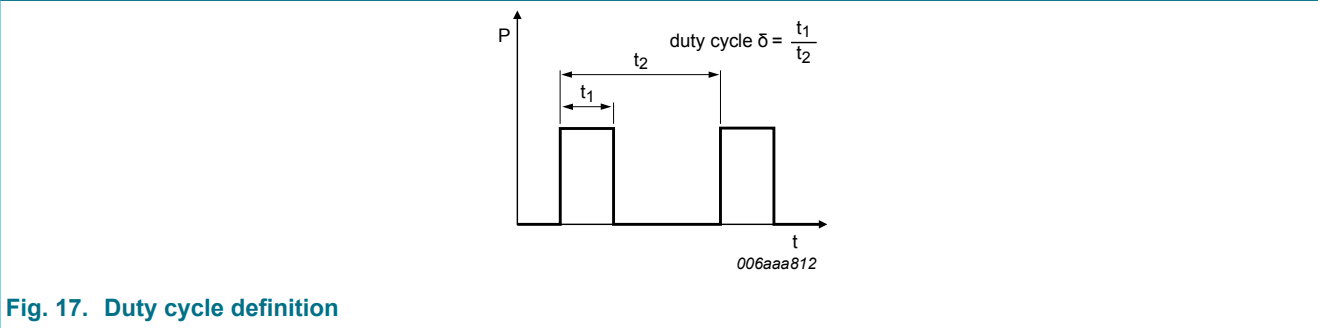


Fig. 17. Duty cycle definition

12. Package outline

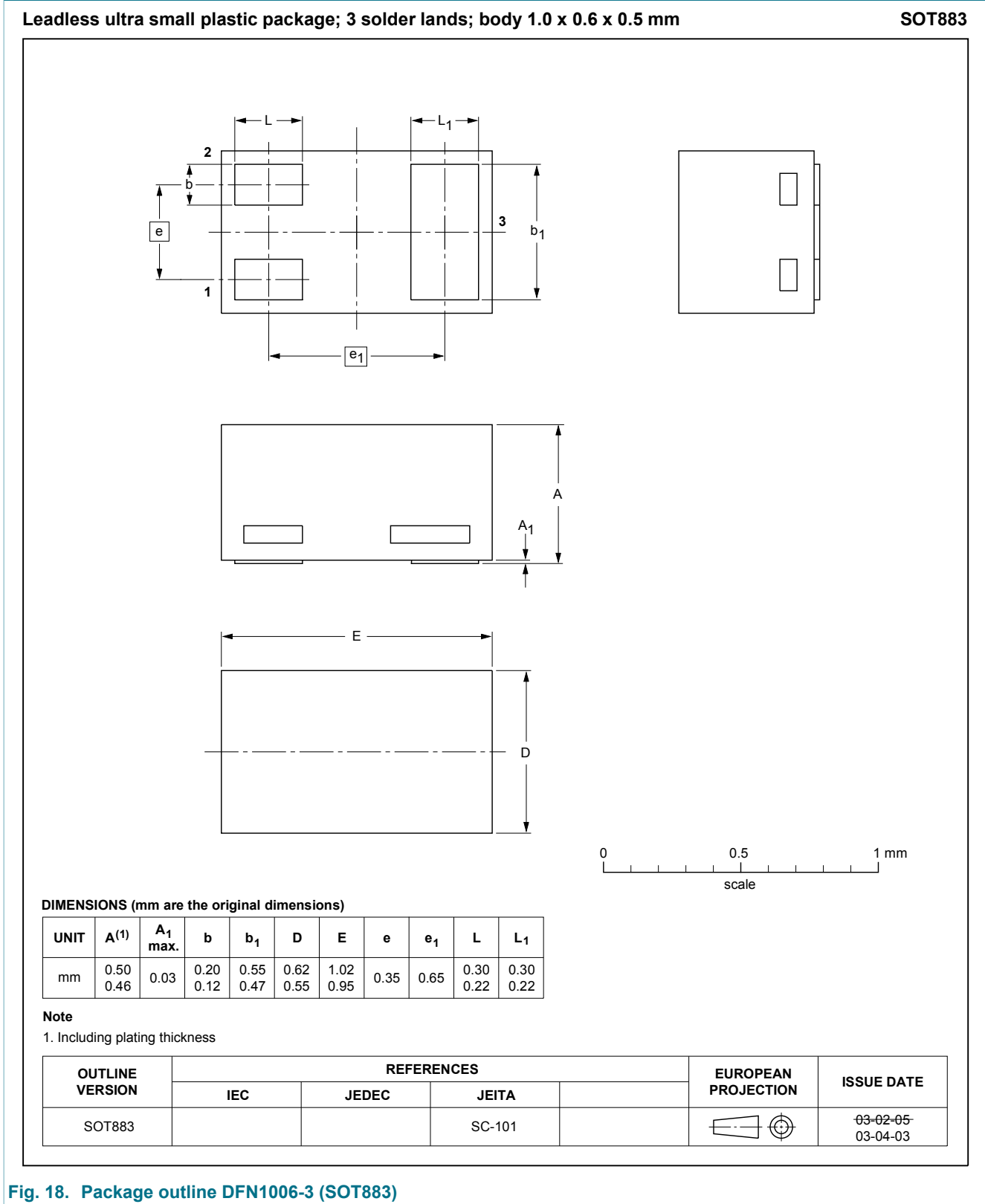


Fig. 18. Package outline DFN1006-3 (SOT883)

13. Soldering

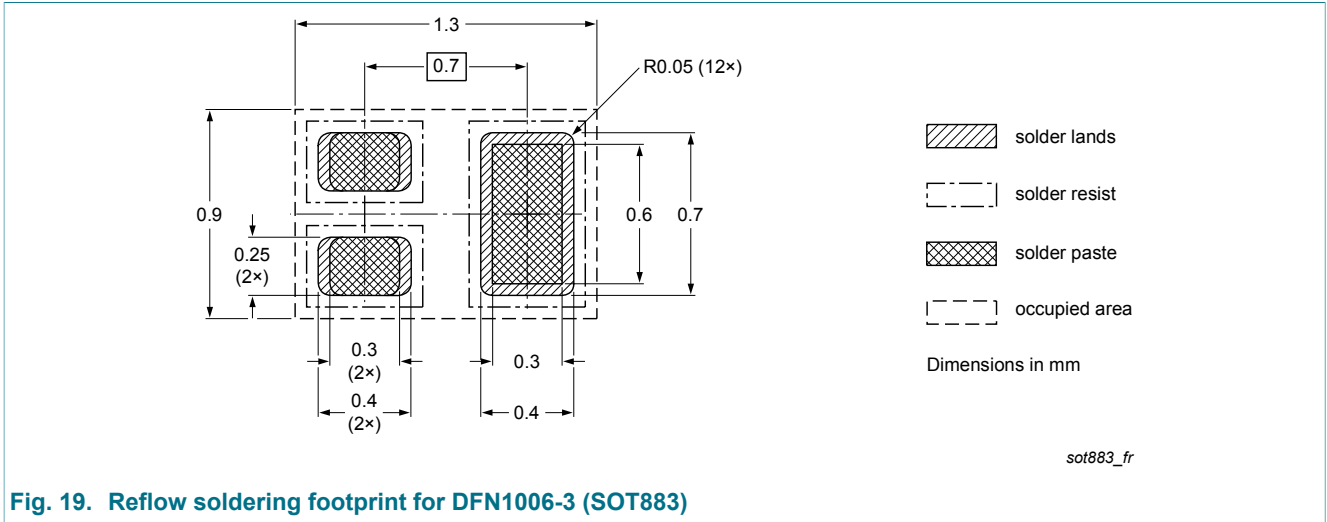


Fig. 19. Reflow soldering footprint for DFN1006-3 (SOT883)

14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status | Change notice | Supersedes |
|---------------|--------------------|--------------------|---------------|---------------|
| NX7002BKM v.2 | 20141203 | Product data sheet | - | NX7002BKM v.1 |
| Modification: | • Figure 3 updated | | | |
| NX7002BKM v.1 | 20141001 | Product data sheet | - | - |

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|--------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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| Product [short] data sheet | Production | This document contains the product specification. |

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